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ABSTRACT OF THE DISCLOSURE

To make thin a circuit device 10 in which are incorporated a plurality of types of circuit elements 12 that differ in thickness, first conductive patterns, onto which comparatively thin circuit elements 12A are mounted, are formed thickly, and second conductive patterns 11B, onto which comparatively thick second circuit elements 12B are mounted, are formed thinly. Also, fine wiring parts may be formed using the thinly formed second conductive patterns 12B. Thus even in the case where thick circuit elements are incorporated, by affixing such circuit elements onto the thinly formed second conductive patterns 11B, the total thickness can be made thin. Thinning of circuit device 10 as a whole can thus be accomplished.